

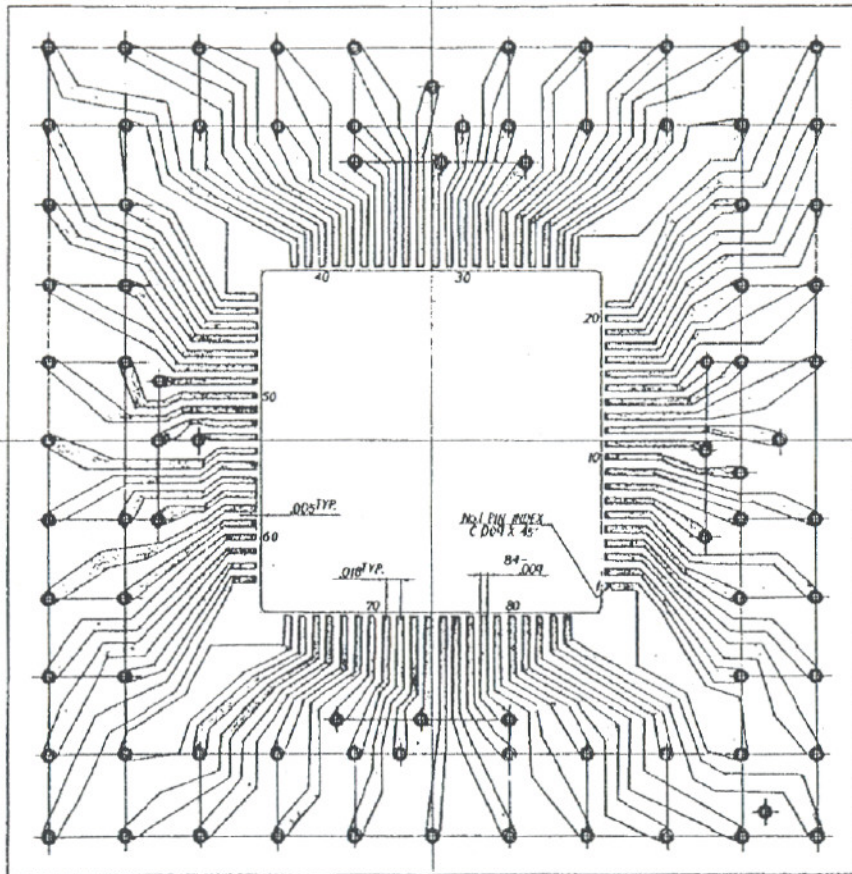
NOTES:  
 1 GOLD PLATING 60μ INCHES MIN THICKNESS OVER  
 100μ INCHES NOMINAL THICKNESS OF NICKEL,  
 UNLESS OTHERWISE SPECIFIED IN PURCHASE  
 ORDER.  
 2 LEAD RESISTANCE:  
 PIN No. 1, 11, 22, 32, 43, 53, 64, 74: ----- 20C mΩ MAX.  
 THE OTHER ----- 500mΩ MAX.

MODIFICATIONS	CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME 84 PIN GRID ARRAY PACKAGE	
SCALE 5 : 1	MATERIAL AS INDICATED

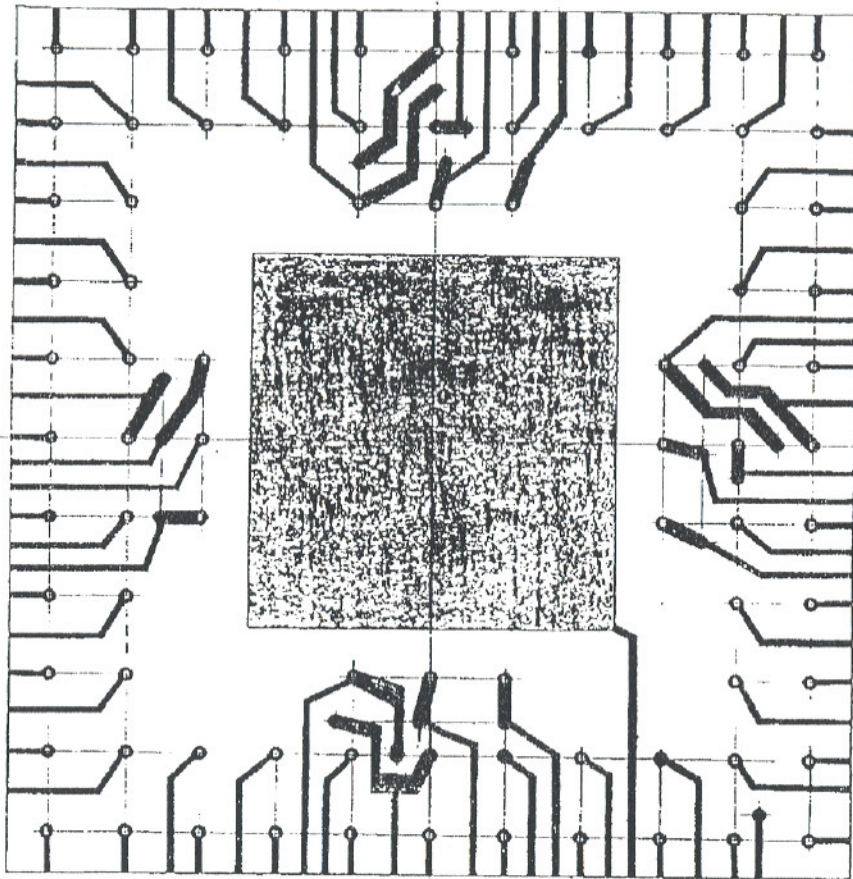
TOLERANCES UNLESS OTHERWISE SPECIFIED ±1.0% N.L.T. ±.005
--

DRAWN T. Yamada	CHECKED T. Atsuki
APPROVED	DATE MAR. 2 '85



MP-2

REVISIONS					NAME	TOLERANCES	DESIGN	CHECKED
					84 PIN GRID ARRAY PACKAGE	UNLESS OTHERWISE SPECIFIED	T. J. TAMURA	T. A. CHU
					SCALE	MATERIAL	APPROVED	DATE
					10:1			MAR 7 '85
CHANGE				DATE	DESIGN	CHECKED	APPROVED	
KYOCERA CORPORATION						KYOTO JAPAN	DWG NO	
							KD-85249	1/4



MP-3

CHANGE	8-PIN GRID ARRAY PACKAGE 10-1	KYOTO JAPAN	MAR 25 RD 88249
	KYOCERA CORPORATION	KYOTO JAPAN	13

WIRE BOND PAD/CONNECTOR PIN INTERCONNECTION PLAN

BOND PAD No.	PIN No.
1	B-2
2	C-2
3	B-1
4	C-1
5	D-2
6	D-1
7	E-3
8	E-2
9	E-1
10	F-2
11	F-3
12	G-3
13	G-1
14	G-2
15	F-1
16	H-1
17	H-2
18	J-1
19	K-1
20	J-2
21	L-1

BOND PAD No.	PIN No.
22	K-2
23	K-3
24	L-2
25	L-3
26	K-4
27	L-4
28	J-5
29	K-5
30	L-5
31	K-6
32	J-6
33	J-7
34	L-7
35	K-7
36	L-6
37	L-8
38	K-8
39	L-9
40	L-10
41	K-9
42	L-11

BOND PAD No.	PIN No.
43	K-10
44	J-10
45	F-11
46	J-11
47	H-10
48	H-11
49	F-10
50	G-10
51	G-11
52	G-9
53	F-9
54	F-11
55	E-11
56	E-10
57	E-9
58	D-11
59	D-10
60	C-11
61	B-11
62	C-10
63	A-11

BOND PAD No.	PIN No.
64	B-10
65	B-9
66	A-10
67	A-9
68	B-8
69	A-8
70	B-6
71	B-7
72	A-7
73	C-7
74	C-6
75	A-6
76	A-5
77	B-5
78	C-5
79	A-4
80	B-4
81	A-3
82	A-2
83	B-3
84	A-1

MODIFICATIONS

CHANGE

DATE DRAWN CHECKED APPROVED

NAME  
**84 PIN GRID ARRAY PACKAGE**

SCALE MATERIAL

TOLERANCES  
UNLESS OTHERWISE SPECIFIED

DRAWN <i>T. Yamashita</i>	CHECKED <i>T. Atsuki</i>
APPROVED	DATE MAR. 2 '85

 KYOCERA CORPORATION

KYOTO  
JAPAN

DWG. NO.  
KD-85249

1/4